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Qnity is Empowering Next-Generation Smart Consumer Electronic Devices with Advanced Interconnect Innovations

Ultra-thin flex circuit materials enable greater design freedom and superior signal integrity

WILMINGTON, Del.--(BUSINESS WIRE)-- Qnity Electronics, Inc. ("Qnity") (NYSE: Q), a premier technology solutions provider across the semiconductor value chain, introduces ultra-thin flex circuit materials that help enable the next generation of smart consumer electronics, including smartphones, AI glasses, and AR/VR devices, through advanced materials innovations that deliver exceptional bendability, mechanical performance, and reliability for advanced interconnect applications.

"Smart consumer electronic device manufacturers are continuously pushing the limits of what is possible in device design," said Chuck Xu, President, Interconnect Solutions. "At Qnity, we do more than solve complex technical challenges. Through continuous innovation, we earn a seat at our customers' design table, where we work closely with customers early in the development process to enable next-generation products with greater functionality, superior user experiences, and differentiated performance."

As smart consumer electronic devices continue to become thinner, lighter, and more feature-rich, manufacturers face increasing challenges in balancing performance, durability, and design flexibility. To address these evolving needs, Qnity has developed ultra-thin material technologies based on Kapton[®] polyimide films and Pyralux[®] flexible laminates that support increasingly complex form factors while maintaining reliable performance.

Qnity's Advanced Flex Technologies portfolio builds on these industry-proven materials to enable advanced applications requiring exceptional optical performance, signal integrity, flexibility, and mechanical durability. As edge AI, intelligent connected devices, and other advanced electronic systems drive greater demands for miniaturization, performance, and reliability, these capabilities give designers greater freedom to integrate more functionality into increasingly compact and complex designs.

At TPCA 2026, October 20–22 in Taipei, Taiwan, Qnity is showcasing its latest ultra-thin flex circuit materials. Visit Booth L213 at TaiNEX 1 (4F) to connect with Qnity technical experts and explore how these advanced materials can help address challenging design requirements while enabling greater design flexibility, signal integrity, and reliability in next-generation smart consumer electronics.

About Qnity

Qnity[™] is a premier technology provider across the semiconductor value chain, empowering AI, high performance computing, and advanced connectivity. From groundbreaking solutions for semiconductor chip manufacturing, to enabling high-speed transmission within complex electronic systems, our high-performance materials and integration expertise make

tomorrow's technologies possible. More information about the company, its businesses and solutions can be found at www.qnityelectronics.com.

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